

**Description**

The SX120N15T uses advanced technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 150V$   $I_D = 120A$

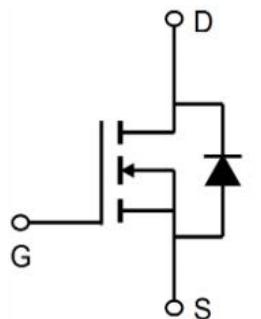
$R_{DS(ON)} < 12m\Omega$  @  $V_{GS}=10V$

**Application**

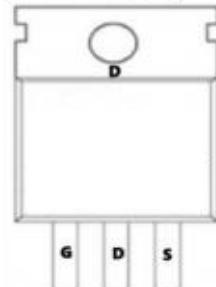
DC/DC Converter

LED Backlighting

Power Management Switches



TO-263-3L

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	120	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	80	A
$I_{DM}$	Pulsed Drain Current	360	A
$E_{AS}$	Single Pulse Avalanche Energy	406	mJ
$I_{AS}$	Avalanche Current	43	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	160	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{eJA}$	Thermal Resistance Junction-Ambient	0.78	°C/W
$R_{eJC}$	Thermal Resistance Junction-Case	62	°C/W

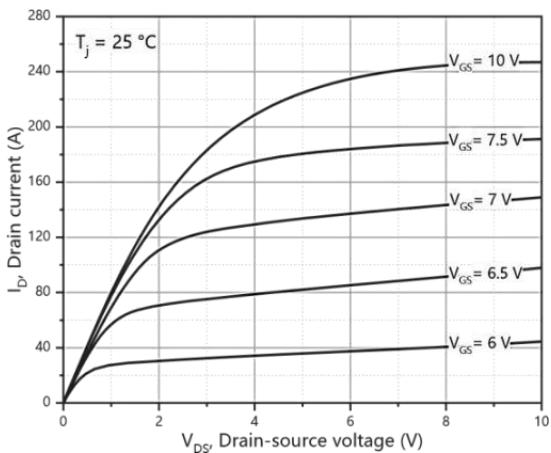
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
VDSS	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	150	168	-	V
IGSS	Gate-body Leakage current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
IDSS	Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
IDSS	Zero Gate Voltage Drain Current $T_J=100^\circ\text{C}$		-	-	100	
VGS(th)	Gate-Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	3.5	4.5	V
RDS(on)	Drain-Source on-Resistance <sup>2</sup>	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	9.5	12	$\text{m}\Omega$
Ciss	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 100\text{KHz}$	-	5469	-	$\text{pF}$
Coss	Output Capacitance		-	1702	-	
Crss	Reverse Transfer Capacitance		-	186	-	
Rg	Gate Resistance	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$	-	1.7	-	$\Omega$
Qg	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 80\text{V}, I_D = 40\text{A}$	-	65.5	-	$\text{nC}$
Qgs	Gate-Source Charge		-	26	-	
Qgd	Gate-Drain Charge		-	17.2	-	
td(on)	Turn-on Delay Time	$V_{GS} = 10\text{V}, V_{DS} = 80\text{V}, R_G = 2\Omega, I_D = 40\text{A}$	-	36	-	$\text{ns}$
tr	Rise Time		-	95	-	
td(off)	Turn-off Delay Time		-	56	-	
tf	Fall Time		-	11	-	
VSD	Diode Forward Voltage <sup>2</sup>	$I_F = 20\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V
IS	Continuous Source Current <sup>1,5</sup>	$V_G = V_D = 0\text{V}$ , Force Current	-	-	120	A
trr	Body Diode Reverse Recovery Time	$V_R = 80\text{V}, I_S = 40\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	76	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	285	-	nC

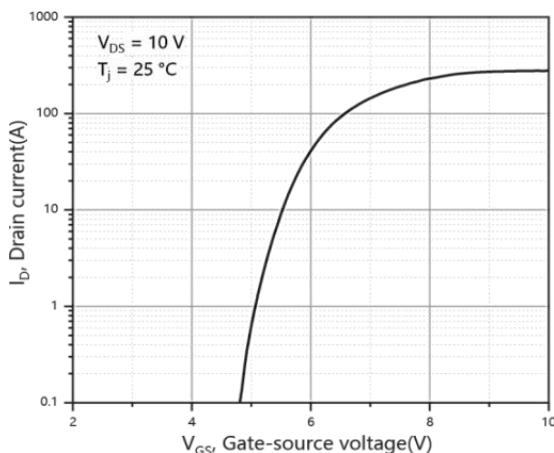
**Notes:**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, I_{AS}=35\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$ junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

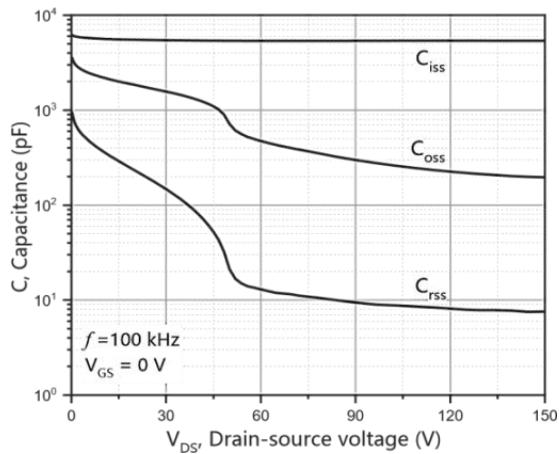
## Typical Characteristics



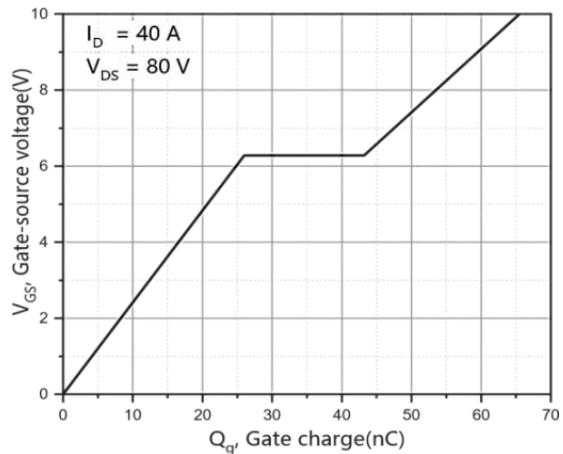
**Figure 1. Type. output characteristics**



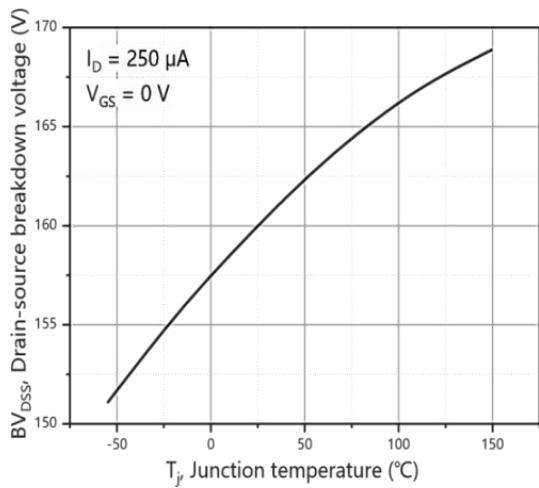
**Figure 2. Type. transfer characteristics**



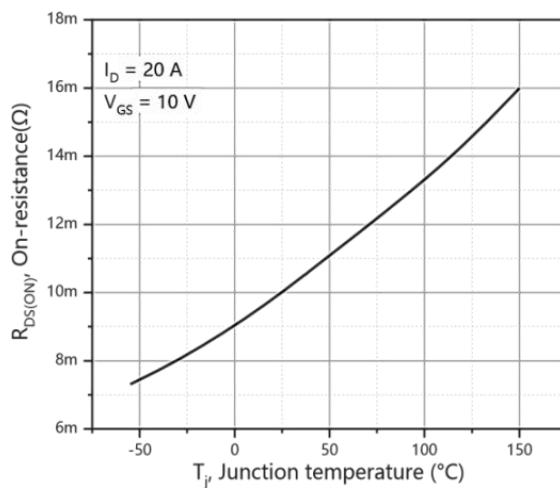
**Figure 3. Type. capacitances**



**Figure 4. Type. gate charge**

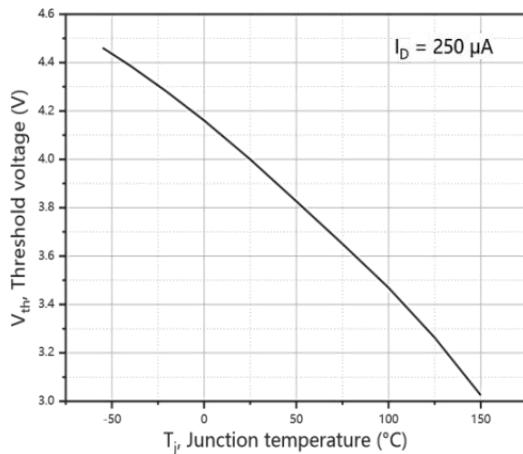


**Figure 5. Drain-source breakdown voltage**

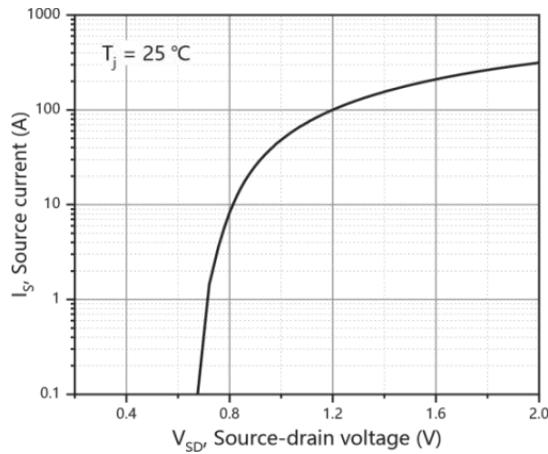


**Figure 6. Drain-source on-state resistance**

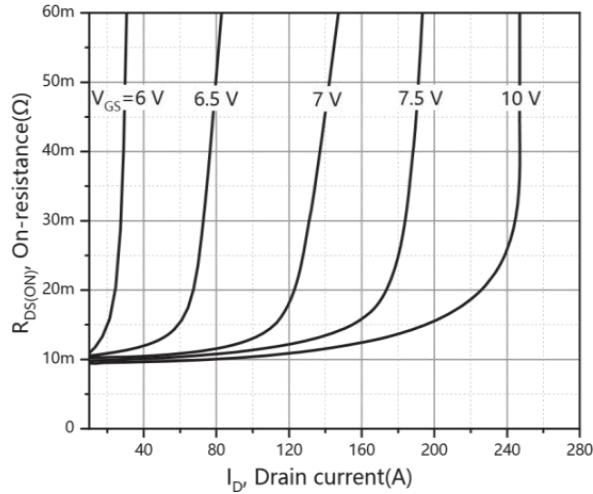
## Typical Characteristics



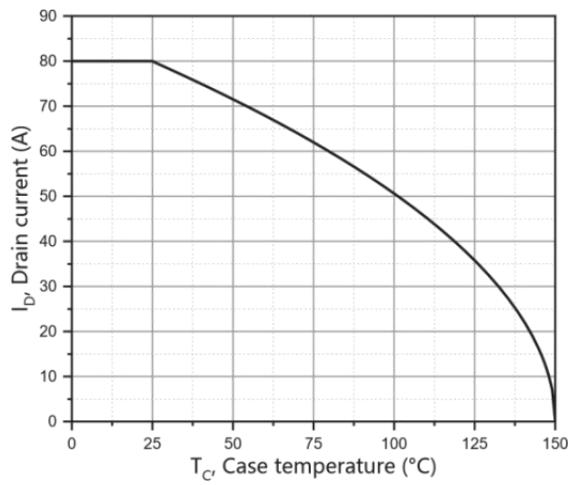
**Figure 7. Threshold voltage**



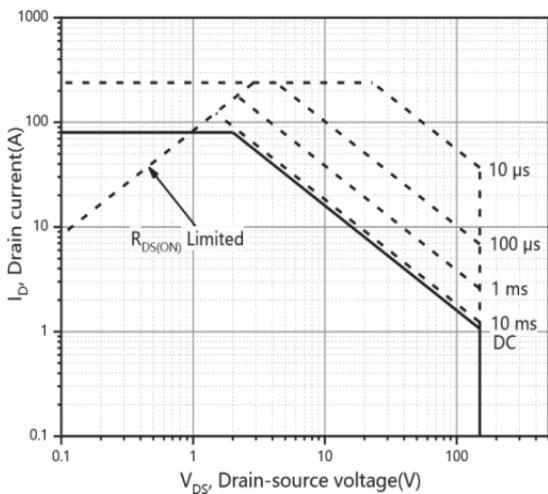
**Figure 8. Forward characteristic of body diode**



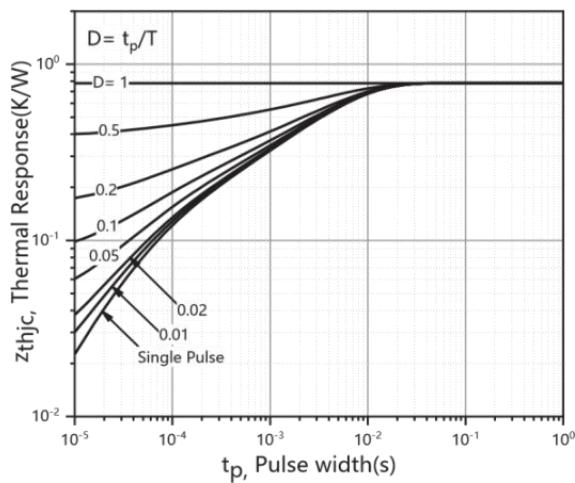
**Figure 9. Drain-source on-state resistance**



**Figure 10. Drain current**

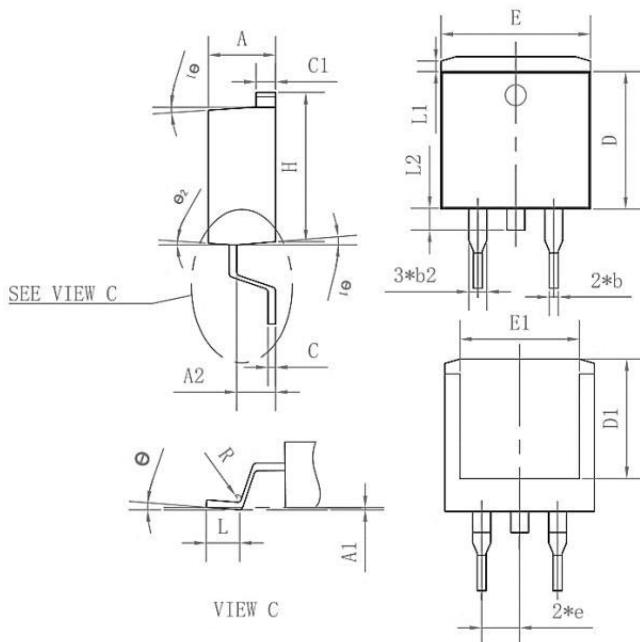


**Figure 11. Safe operation area  $T_C=25^\circ C$**



**Figure 12. Max. transient thermal impedance**

## Package Mechanical Data-TO-263-3L-SLK



Symbol	Common mm		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4°	8°
Θ1	4°	7°	10°
Θ2	0°	3°	6°

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800